

NOTES:

1.MATERIAL:

HOUSING--HIGH TEMP THERMAL PLASTIC,
UL 94V-0, NATURE;
TERMINAL--COPPER ALLOY;
SHELL--COPPER ALLOY;

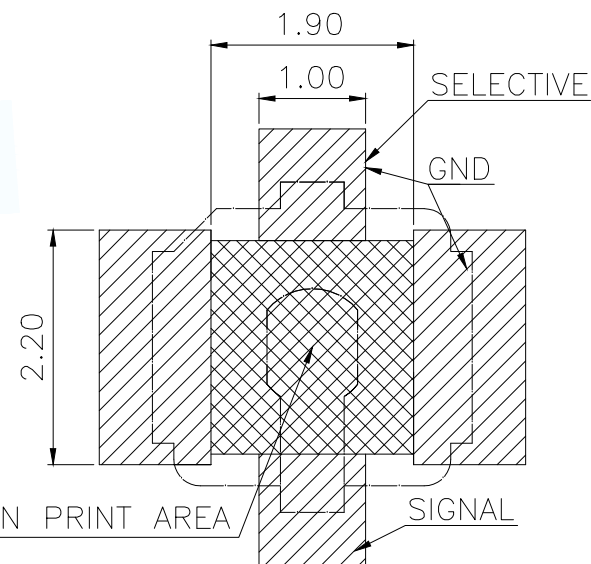
2.PLATING:

TERMINAL--G/F PLATING ON CONTACT AREA
G/F PLATING ON SOLDER TAIL AREA
ALL OVER 1.27 MICRON MIN.
NICKEL PLATING;

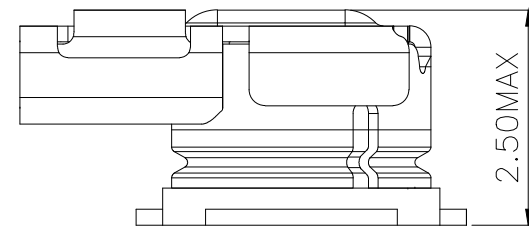
SHELL--G/F PLATING OVER ALL;

3.PATENT PRODUCT PROHIBIT COPYING:

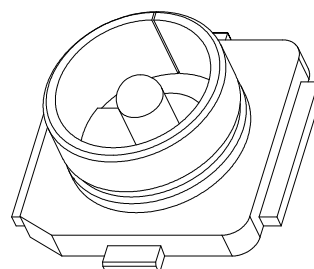
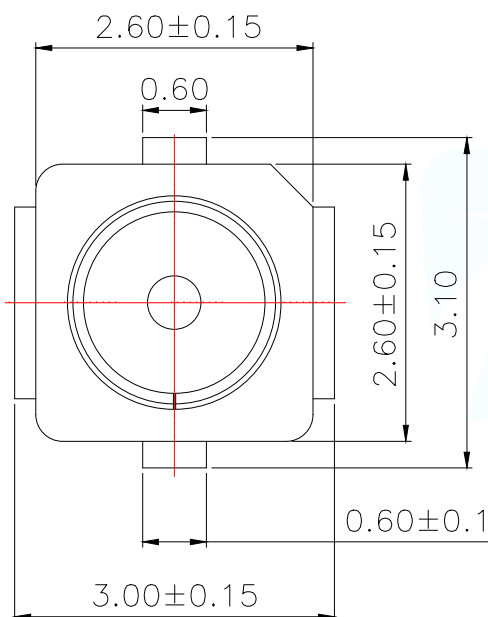
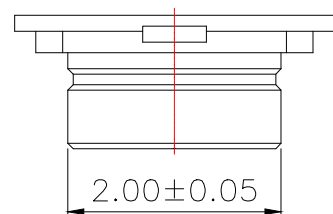
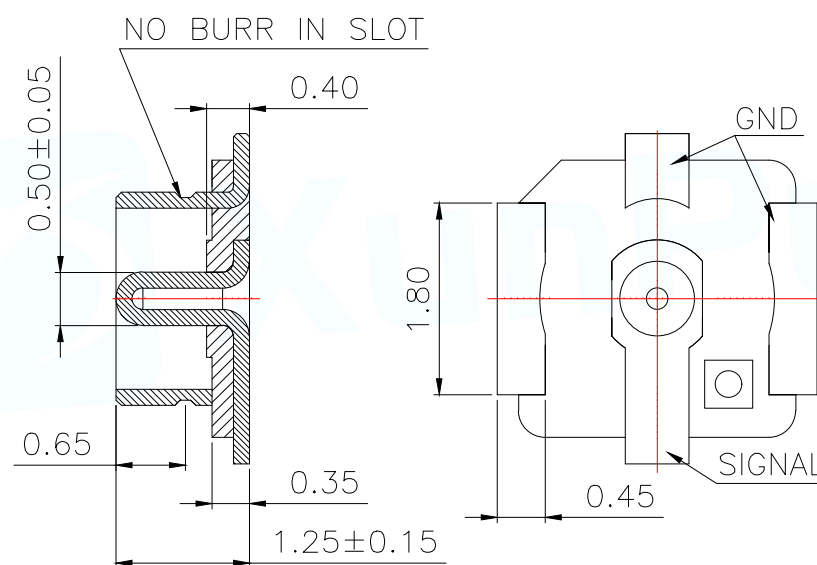
3SMT/4SMT PCB LAYOUT
FULLY COMPATIBLE



RECOMMEND PCB LAYOUT
TOLERANCE: $\pm 0.05\text{MM}$



MATING INTERFACE



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: RF CONN GEN I 4SMT TYPE		
			PAR	U.FL-IPEX-1	
DECIMALS:	ANGLES:		DWN	Lucas	
.X:±0.38	±2°		CHKD	Ethan	
.XX:±0.20			APVD	Jacob	
.XXX:±0.10		CUSTOMER COPY	SCALE1:1	UNIT:MM	
			SIZE:A4	SHEET:1F1	REV:A